

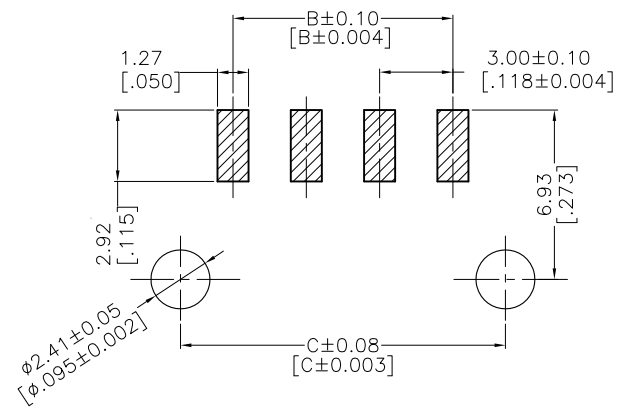
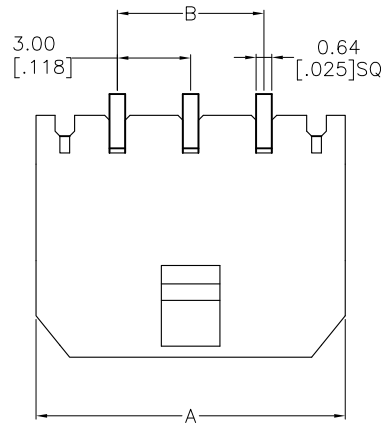
# HSF

**NOTES:**

Current Rating:5.0A AMP  
 Contact Resistance:10milliohm Max  
 Withstand Voltage:1000V AC/Minute  
 Insulation Resistance:1000Megohm Min  
 Operation Temperature:-25°C to +85°C

Housing Material:LCP+30%GF(UL94V-0)  
 Contact Material:Copper alloy  
 Contact plating:Au/Sn over Ni Plating

**RECOMMENDED PCB LAYOUT**  
 TOLERANCE IS ±0.05



WF3001-1WZXXBX1

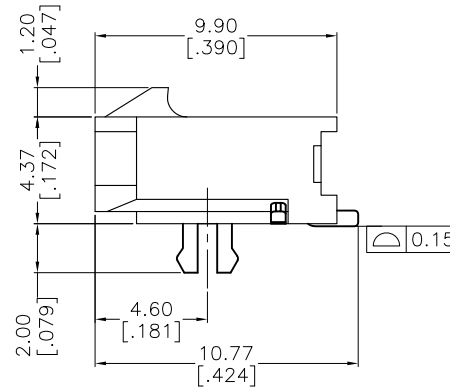
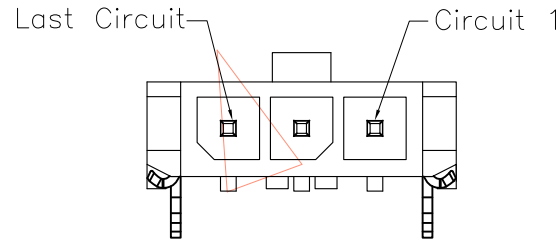
## Ordering Information

**WF3001-1 WZ XX B X 2**

Terminal shape:  
 WZ:Wafer 90° SMT

NO.of Pins  
 02~12Pin

Packing:  
 0=PE Bag  
 T=Tube  
 A=Tray  
 R=Tape&Reel



Circuit	A	B	C
02	9.65[0.380]	3.00[0.118]	7.30[0.287]
03	12.65[0.498]	6.00[0.236]	10.30[0.405]
04	15.65[0.616]	9.00[0.355]	13.30[0.524]
05	18.65[0.735]	12.00[0.473]	16.30[0.642]
06	21.65[0.853]	15.00[0.591]	19.30[0.760]
07	24.65[0.971]	18.00[0.709]	22.30[0.878]
08	27.65[1.089]	21.00[0.827]	25.30[0.996]
09	30.65[1.207]	24.00[0.945]	28.30[1.114]
10	33.65[1.325]	27.00[1.063]	31.30[1.232]
11	36.65[1.443]	30.00[1.181]	34.30[1.350]
12	39.65[1.561]	33.00[1.299]	37.30[1.469]

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION		DRAW FZY	DATE	SCALE	1:1	PART NO.
				X.X	±0.40					
A1	2012.05.03	料号由WF3001-1WZHXXBX2变更为WF3001-1WZXXBX2	Atomy	X.XX	±0.25	CHECK	2012.05.03	UNIT	mm inch	△WF3001-1WZXXBX2
A0	2011.12.20	NEW	-	X.XXX	±0.15	APPROVE	DATE	SHEET	1/1	TITLE: 3.0 Wafer Single Row 90° SMT With Clip
				Angle	± 3'					
				DIM	TOL			PROJ.		